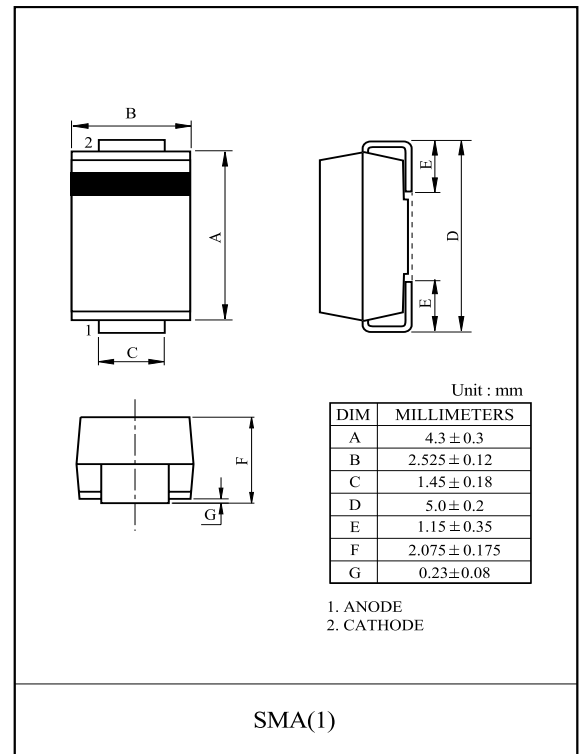


FEATURES

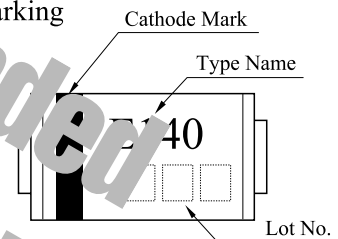
- Plastic package has Underwriters Laboratory flammability Classification 94V-0.
- For surface mounted applications.
- Low profile package.
- Built-in strain relief, ideal for automated placement.
- Glass passivated chip junction.
- High temperature soldering guaranteed
: 250 /10 seconds at terminals.

MAXIMUM RATING (Ta=25)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive peak reverse voltage	V_{RRM}	400	V
RMS voltage	V_{RMS}	280	V
DC blocking voltage	V_{DC}	400	V
Average forward rectified current (see fig.1)	$I_{F(AV)}$	1	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) $T_L=110$	I_{FSM}	4	A
Operating Junction and Storage Temperature Range	T_j, T_{stg}	-55~150	



Marking



ELECTRICAL CHARACTERISTICS (Ta=25)

CHARACTERISTIC	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Forward voltage	V_F	$I_F=1A$	-	-	1.1	V
Leakage current	I_R	$V_{RRM}=400V$	-	-	1.0	μA
			-	-	50	
Reverse recovery time	t_{rr}	$I_F=0.5A, I_R=1.0A$	-	1.8	-	μs
Junction capacitance	C_j	$V_R=4.0V, f=1MHz$	-	12	-	pF
Thermal resistance	$R_{th(A)}$ (Note1)	Junction to ambient	-	-	75	/W
	$R_{th(L)}$	Junction to lead	-	-	27	

Note 1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B with (5.0 × 5.0mm) copper pads.

Fig.1 Forward Current Derating Curve

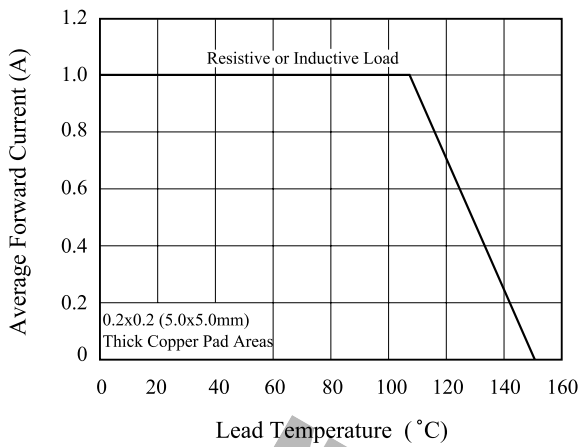


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

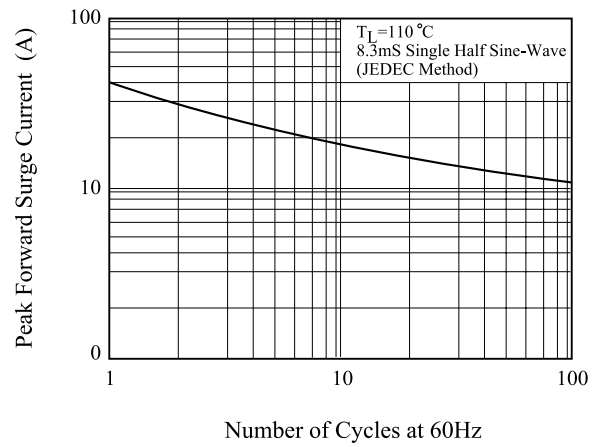


Fig.3 Typical Instantaneous Forward Characteristics

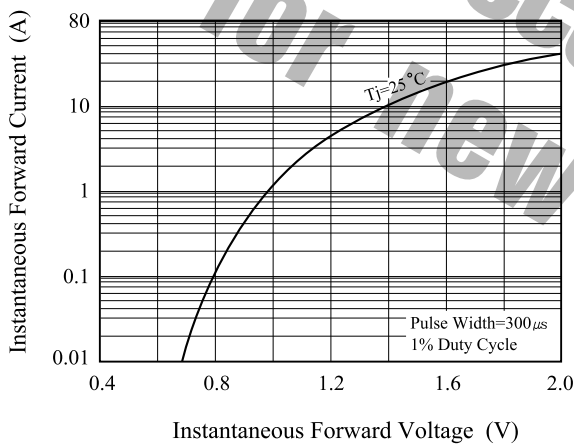


Fig.4 Typical Reverse Leakage Characteristics

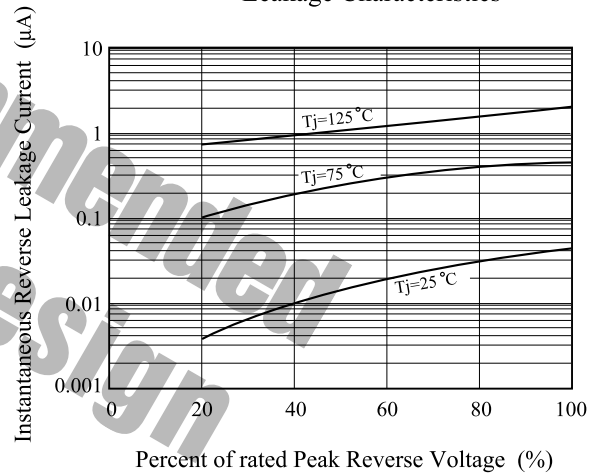


Fig.5 Typical Junction Capacitance

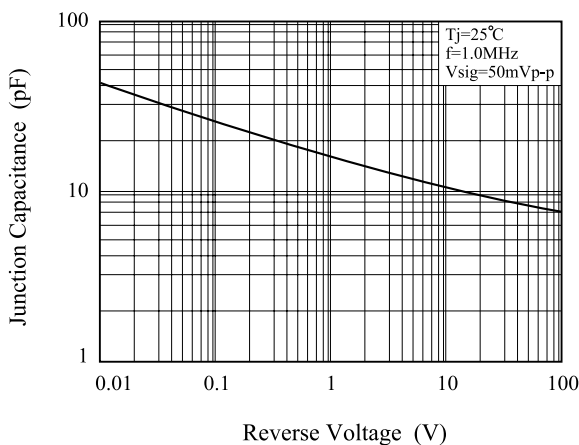


Fig.6 Transient Thermal Impedance

